



THS4521 THS4524

SBOS458B-DECEMBER 2008-REVISED MAY 2009

VERY LOW POWER, NEGATIVE RAIL INPUT, RAIL-TO-RAIL OUTPUT, FULLY DIFFERENTIAL AMPLIFIER

FEATURES

- Fully Differential Architecture
- Bandwidth: 145 MHz
- Slew Rate: 490 V/us
- HD_2 : -133 dBc at 10 kHz (1 V_{RMS}, R_L = 1 k Ω)
- HD₃: -140 dBc at 10 kHz (1 V_{RMS}, R_L = 1 k Ω)
- Input Voltage Noise: 4.6 nV/ \sqrt{Hz} (f = 100 kHz)
- **NRI—Negative Rail Input**
- **RRO**—Rail-to-Rail Output
- **Output Common-Mode Control (with Low** Offset and Drift)
- Power Supply:
 - Voltage: +2.5 V (±1.25 V) to +5.5 V (±2.75 V)
 - Current: 1.14 mA/ch
- Power-Down Capability: 20 µA (typ)

THS4521 and ADS1278 Combined Performance



APPLICATIONS

- Low-Power SAR and $\Delta\Sigma$ ADC Drivers
- Low-Power Differential Driver
- Low-Power Differential Signal Conditioning

DESCRIPTION

The THS4521, THS4522, and THS4524 family of devices are very low-power, fully differential op amps with rail-to-rail output and an input common-mode range that includes the negative rail. These amplifiers are designed for low-power data acquisition systems and high-density applications where power dissipation is a critical parameter.

The family includes single (THS4521), dual (THS4522), and quad (THS4524) versions.

These fully differential op amps feature accurate output common-mode control that allows for dc-coupling when driving analog-to-digital converters (ADCs). This control, coupled with an input common-mode range below the negative rail as well as rail-to-rail output, allows for easy interfacing between single-ended, ground-referenced signal sources. Additionally, these devices are ideally suited for driving both successive-approximation register (SAR) and delta-sigma ($\Delta\Sigma$) ADCs using only a single +3V to +5V and ground power supply.

The THS4521, THS4522, and THS4524 family of fully differential op amps is characterized for operation over the full industrial temperature range from -40°C to +85°C.

RELATED PRODUCTS

DEVICE	BW (MHz)	l _Q (mA)	THD (dBc) at 100 kHz	V _N (nV/√Hz)	RAIL- TO-RAIL
THS4520	570	15.3	-114	2	Out
THS4121	100	16	-79	5.4	In/Out
THS4130	150	16	-107	1.3	No

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THS4521 THS4522 THS4524



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This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PRODUCT	PACKAGE- LEAD	PACKAGE DESIGNATOR	SPECIFIED TEMPERATURE RANGE	PACKAGE MARKING	ORDERING NUMBER	TRANSPORT MEDIA, QUANTITY
	SOIC-8	D		TH4521	THS4521ID	Rails, 75
THS4521	5010-8	D	-40°C to +85°C	1 8452 1	THS4521IDR	Tape and reel, 2500
1H54521	MSOP-8	DGK	-40 C 10 +85 C	4521	THS4521IDGKT	Tape and reel, 250
	MSOP-8	DGK			THS4521IDGKR	Tape and reel, 2500
THS4522	TSSOP-16	PW	40%C to 195%C	TUC 4522	THS4522IPW	Rails, 90
11154522	1350P-16	PVV	-40°C to +85°C	THS4522	THS4522IPWR	Tape and reel, 2000
THS4524	TSSOP-38	DBT	-40°C to +85°C	THS4524	THS4524IDBT	Rails, 50
1054524	1350P-36	DBT	-40°C 10 +85°C	1004024	THS4524IDBTR	Tape and reel, 2000

PACKAGE/ORDERING INFORMATION⁽¹⁾

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

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Over operating free-air temperature range (unless otherwise noted).

	PARAMETER	THS4521, THS4522. THS4524	UNIT	
Supply V	'oltage, V_{S-} to V_{S+}	5.5	V	
Input Vol	tage, V _I	±Vs	V	
Differenti	ial Input Voltage, V _{ID}	1	V	
Output C	current, I _O	100	mA	
Continuo	us Power Dissipation	See Thermal Characteristic Specifications		
Maximun	n Junction Temperature, T _J	+150	°C	
Maximun	n Junction Temperature, T _J (continuous operation, long-term reliability)	+125	°C	
Operatin	g Free-air Temperature Range, T _A	-40 to +85	°C	
Storage ⁻	Temperature Range, T _{STG}	-65 to +150	°C	
Lead Ter	mperature [1,6 mm (1/16 inch) from case for 10 seconds]	300	°C	
	Human Body Model (HBM)	1300	V	
ESD Rating:	Charge Device Model (CDM)	1000	V	
rtaung.	Machine Model (MM)	50	V	

(1) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.



ELECTRICAL CHARACTERISTICS: $V_{S+} - V_{S-} = 3.3 V$

At $V_{S+} = +3.3 \text{ V}$, $V_{S-} = 0 \text{ V}$, $V_{OCM} = \text{open}$, $V_{OUT} = 2 \text{ V}_{PP}$ (differential), $R_L = 1 \text{ k}\Omega$ differential, G = 1 V/V, single-ended input, differential output, input and output referenced to midsupply, unless otherwise noted.

		THS452	1, THS4522,	THS4524		TEST
PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT	LEVEL ⁽¹⁾
AC PERFORMANCE						
Small-Signal Bandwidth	$V_{OUT} = 100 \text{ mV}_{PP}, \text{ G} = 1$		135		MHz	С
	V _{OUT} = 100 mV _{PP} , G = 2		49		MHz	С
	$V_{OUT} = 100 \text{ mV}_{PP}, \text{ G} = 5$		18.6		MHz	С
	$V_{OUT} = 100 \text{ mV}_{PP}, \text{ G} = 10$		9.3		MHz	С
Gain Bandwidth Product	$V_{OUT} = 100 \text{ mV}_{PP}, \text{ G} = 10$		93		MHz	С
Large-Signal Bandwidth	$V_{OUT} = 2 V_{PP}, G = 1$		95		MHz	С
Bandwidth for 0.1-dB Flatness	$V_{OUT} = 2 V_{PP}, G = 1$		20		MHz	С
Rising Slew Rate (Differential)	V_{OUT} = 2-V Step, G = 1, R _L = 200 Ω		420		V/µs	С
Falling Slew Rate (Differential)	V_{OUT} = 2-V Step, G = 1, R _L = 200 Ω		460		V/µs	С
Overshoot	V_{OUT} = 2-V Step, G = 1, R _L = 200 Ω		1.2		%	С
Undershoot	V_{OUT} = 2-V Step, G = 1, R _L = 200 Ω		2.1		%	С
Rise Time	V_{OUT} = 2-V Step, G = 1, R _L = 200 Ω		4		ns	С
Fall Time	V_{OUT} = 2-V Step, G = 1, R _L = 200 Ω		3.5		ns	С
Settling Time to 1%	V_{OUT} = 2-V Step, G = 1, R _L = 200 Ω		13		ns	С
Harmonic Distortion						
2nd harmonic	$f = 10 \text{ kHz}, \text{ V}_{OUT} = 1 \text{ V}_{RMS}$		-133		dBc	С
	$f = 1 \text{ MHz}, \text{ V}_{OUT} = 2 \text{ V}_{PP}$		-85		dBc	С
3rd harmonic	$f = 10 \text{ kHz}, \text{ V}_{OUT} = 1 \text{ V}_{RMS}$		-140		dBc	С
	$f = 1 \text{ MHz}, \text{ V}_{OUT} = 2 \text{ V}_{PP}$		-90		dBc	С
Second-Order Intermodulation Distortion	Two-tone, $f_1 = 2$ MHz, $f_2 = 2.2$ MHz, V _{OUT} = 2-V _{PP} envelope		-83		dBc	С
Third-Order Intermodulation Distortion	Two-tone, $f_1 = 2 \text{ MHz}$, $f_2 = 2.2 \text{ MHz}$, $V_{OUT} = 2 \cdot V_{PP}$ envelope		-90		dBc	С
Input Voltage Noise	f > 10 kHz		4.6		nV/√Hz	С
Input Current Noise	f > 100 kHz		0.6		pA/√Hz	С
Overdrive Recovery Time	Overdrive = ± 0.5 V		80		ns	С
Output Balance Error	V_{OUT} = 100 mV, f ≤ 2 MHz (differential input)		-57		dB	С
Closed-Loop Output Impedance	f = 1 MHz (differential)		0.3		Ω	С
Channel-to-Channel Crosstalk (THS4522, THS4524)	f = 10 kHz, measured differentially		-125		dB	С
DC PERFORMANCE						
Open-Loop Voltage Gain (A _{OL})		100	116		dB	А
Input-Referred Offset Voltage	$T_A = +25^{\circ}C$		±0.2	±2	mV	А
	$T_{A} = -40^{\circ}C \text{ to } +85^{\circ}C$		±0.5	±3.5	mV	В
Input offset voltage drift ⁽²⁾	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$		±2		μV/°C	С
Input Bias Current	$T_A = +25^{\circ}C$		0.65	0.85	μA	В
	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$		0.75	0.95	μA	В
Input bias current drift ⁽²⁾	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$		±1.75	±2	nA/°C	В
Input Offset Current	$T_A = +25^{\circ}C$		±50	±60	pА	В
	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$		±60	±70	pА	В
Input offset current drift ⁽²⁾	$T_{A} = -40^{\circ}C \text{ to } +85^{\circ}C$		±0.16	±0.25	pA/°C	В

(1) Test levels: (A) 100% tested at +25°C. Over temperature limits set by characterization and simulation. (B) Limits set by characterization and simulation. (C) Typical value only for information.

(2) Input Offset Voltage Drift, Input Bias Current Drift, and Input Offset Current Drift are average values calculated by taking data at -40°C and +85°C, computing the difference, and dividing by 125.



ELECTRICAL CHARACTERISTICS: $V_{S+} - V_{S-} = 3.3 V$ (continued)

At $V_{S+} = +3.3 \text{ V}$, $V_{S-} = 0 \text{ V}$, $V_{OCM} = \text{open}$, $V_{OUT} = 2 \text{ V}_{PP}$ (differential), $R_L = 1 \text{ k}\Omega$ differential, G = 1 V/V, single-ended input, differential output, input and output referenced to midsupply, unless otherwise noted.

		THS452	1, THS4522, ⁻	THS4524		TEST
PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT	LEVEL ⁽¹⁾
INPUT						
Common-Mode Input Voltage Low	T _A = +25°C		-0.2	-0.1	V	А
	$T_{A} = -40^{\circ}C \text{ to } +85^{\circ}C$		-0.1	0	V	В
Common-Mode Input Voltage High	T _A = +25°C	1.9	2		V	А
	$T_A = -40^{\circ}C$ to $+85^{\circ}C$	1.8	1.9		V	В
Common-Mode Rejection Ratio (CMRR)		80	100		dB	А
Input Resistance			110 1.5		kΩpF	С
OUTPUT						
Output Voltage Low	T _A = +25°C		0.08	0.15	V	А
	$T_{A} = -40^{\circ}C \text{ to } +85^{\circ}C$		0.09	0.2	V	В
Output Voltage High	T _A = +25°C	3.0	3.1		V	А
	$T_A = -40^{\circ}C$ to $+85^{\circ}C$	2.95	3.05		V	В
Output Current Drive (for linear operation)	$R_{L} = 50 \ \Omega$		±35		mA	С
POWER SUPPLY	-					
Specified Operating Voltage		2.5		5.5	V	В
Quiescent Operating Current, per channel	T _A = +25°C	0.9	1.0	1.2	mA	А
	$T_A = -40^{\circ}C$ to $+85^{\circ}C$	0.85	1.0	1.25	mA	В
Power-Supply Rejection Ratio (±PSRR)		80	100		dB	А
POWER DOWN						
Enable Voltage Threshold	Assured on above 2.1 V		1.6	2.1	V	А
Disable Voltage Threshold	Assured off below 0.7 V	0.7	1.6		V	А
Disable Pin Bias Current			1		μA	С
Power Down Quiescent Current			10		μΑ	С
Turn-On Time Delay	Time to V_{OUT} = 90% of final value, V_IN= 2 V, R_L = 200 Ω		108		ns	В
Turn-Off Time Delay	Time to V_{OUT} = 10% of original value, V_{IN} = 2 V, R_L = 200 Ω		88		ns	В
V _{OCM} VOLTAGE CONTROL						
Small-Signal Bandwidth			23		MHz	С
Slew Rate			55		V/µs	С
Gain		0.98	0.99	1.02	V/V	А
Common-Mode Offset Voltage from V_{OCM} Input	Measured at V _{OUT} with V _{OCM} input driven, V _{OCM} = 1.65 V ±0.5 V		±2.5	±4	mV	В
Input Bias Current	$V_{OCM} = 1.65 \text{ V} \pm 0.5 \text{ V}$		±5	±8	μΑ	В
V _{OCM} Voltage Range		1	0.8 to 2.5	2.3	V	А
Input Impedance			72 1.5		kΩ∎pF	С
Default Output Common-Mode Voltage Offset from (V_{S+}-V_{S-})/2	Measured at V_{OUT} with V_{OCM} input open		±1.5	±5	mV	A
THERMAL CHARACTERISTICS						
Specified Operating Range All Packages			-40 to +85		°C	С
Thermal Resistance, θ_{JA}	Junction-to-ambient					
THS4521 D SO-8			194		°C/W	С
DGK MSOP-8			269		°C/W	С
THS4522 PW TSSOP-16			116		°C/W	С
THS4524 DBT TSSOP-38			81		°C/W	С

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ELECTRICAL CHARACTERISTICS: $V_{S+} - V_{S-} = 5 V$

At $V_{S+} = +5 \text{ V}$, $V_{S-} = 0 \text{ V}$, $V_{OCM} = \text{open}$, $V_{OUT} = 2 \text{ V}_{PP}$ (differential), $R_F = 1 \text{ k}\Omega$, $R_L = 1 \text{ k}\Omega$ differential, G = 1 V/V, single-ended input, differential output, input and output referenced to midsupply, unless otherwise noted.

		THS452	1, THS4522,	THS4524		TEST	
PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT	LEVEL ⁽¹⁾	
AC PERFORMANCE							
Small-Signal Bandwidth	V_{OUT} = 100 m V_{PP} , G = 1		145		MHz	С	
	V_{OUT} = 100 m V_{PP} , G = 2		50		MHz	С	
	V_{OUT} = 100 m V_{PP} , G = 5		20		MHz	С	
	$V_{OUT} = 100 \text{ mV}_{PP}, \text{ G} = 10$		9.5		MHz	С	
Gain Bandwidth Product	$V_{OUT} = 100 \text{ mV}_{PP}, \text{ G} = 10$		95		MHz	С	
Large-Signal Bandwidth	$V_{OUT} = 2 V_{PP}, G = 1$		145		MHz	С	
Bandwidth for 0.1-dB Flatness	$V_{OUT} = 2 V_{PP}, G = 1$		30		MHz	С	
Rising Slew Rate (Differential)	V_{OUT} = 2-V Step, G = 1, R _L = 200 Ω		490		V/µs	С	
Falling Slew Rate (Differential)	V_{OUT} = 2-V Step, G = 1, R _L = 200 Ω		600		V/µs	С	
Overshoot	V_{OUT} = 2-V Step, G = 1, R _L = 200 Ω		1		%	С	
Undershoot	V_{OUT} = 2-V Step, G = 1, R _L = 200 Ω		2.6		%	С	
Rise Time	V_{OUT} = 2-V Step, G = 1, R _L = 200 Ω		3.4		ns	С	
Fall Time	V_{OUT} = 2-V Step, G = 1, R _L = 200 Ω		3		ns	С	
Settling Time to 1%	V_{OUT} = 2-V Step, G = 1, R _L = 200 Ω		10		ns	С	
Harmonic Distortion							
2nd harmonic	$f = 10 \text{ kHz}, \text{ V}_{OUT} = 1 \text{ V}_{RMS}$		-133		dBc	С	
	$f = 1 MHz, V_{OUT} = 2 V_{PP}$		-85		dBc	С	
3rd harmonic	$f = 10 \text{ kHz}, \text{ V}_{OUT} = 1 \text{ V}_{RMS}$		-140		dBc	С	
	$f = 1 MHz, V_{OUT} = 2 V_{PP}$		-91		dBc	С	
Second-Order Intermodulation Distortion	Two-tone, $f_1 = 2$ MHz, $f_2 = 2.2$ MHz, $V_{OUT} = 2$ - V_{PP} envelope		-86		dBc	С	
Third-Order Intermodulation Distortion	Two-tone, $f_1 = 2$ MHz, $f_2 = 2.2$ MHz, $V_{OUT} = 2 \cdot V_{PP}$ envelope		-93		dBc	С	
Input Voltage Noise	f > 10 kHz		4.6		nV/√Hz	С	
Input Current Noise	f > 100 kHz		0.6		pA/√Hz	С	
Overdrive Recovery Time	Overdrive = ± 0.5 V		75		ns	С	
Output Balance Error	V_{OUT} = 100 mV, f < 2 MHz, V_{IN} differential		-57		dB	С	
Closed-Loop Output Impedance	f = 1 MHz (differential)		0.3		Ω	С	
Channel-to-Channel Crosstalk (THS4522. THS4524)	f = 10 kHz, measured differentially		-125		dB	С	
DC PERFORMANCE							
Open-Loop Voltage Gain (A _{OL})		100	119		dB	А	
Input-Referred Offset Voltage	T _A = +25°C		±0.24	±2	mV	А	
	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$		±0.5	±3.5	mV	В	
Input offset voltage drift ⁽²⁾	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$		±2		μV/°C	В	
Input Bias Current	T _A = +25°C		0.7	0.9	μA	В	
	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$		0.9	1.1	μΑ	В	
Input bias current drift ⁽²⁾	$T_{A} = -40^{\circ}C \text{ to } +85^{\circ}C$		±1.8	±2.2	nA/°C	В	
Input Offset Current	$T_A = +25^{\circ}C$		±50	±60	pА	В	
	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$		±60	±75	pА	В	
Input offset current drift ⁽²⁾	$T_{A} = -40^{\circ}C \text{ to } +85^{\circ}C$		±0.16	±0.25	pA/°C	В	

(1) Test levels: (A) 100% tested at +25°C. Over temperature limits set by characterization and simulation. (B) Limits set by characterization and simulation. (C) Typical value only for information.

(2) Input Offset Voltage Drift, Input Bias Current Drift, and Input Offset Current Drift are average values calculated by taking data at -40°C and +85°C, computing the difference, and dividing by 125.



ELECTRICAL CHARACTERISTICS: $V_{S+} - V_{S-} = 5 V$ (continued)

At $V_{S+} = +5 \text{ V}$, $V_{S-} = 0 \text{ V}$, $V_{OCM} = \text{open}$, $V_{OUT} = 2 \text{ V}_{PP}$ (differential), $R_F = 1 \text{ k}\Omega$, $R_L = 1 \text{ k}\Omega$ differential, G = 1 V/V, single-ended input, differential output, input and output referenced to midsupply, unless otherwise noted.

		THS452	1, THS4522,	THS4524		TEST
PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT	LEVEL ⁽¹⁾
INPUT						
Common-Mode Input Voltage Low	T _A = +25°C		-0.2	-0.1	V	А
	$T_{A} = -40^{\circ}C \text{ to } +85^{\circ}C$		-0.1	0	V	В
Common-Mode Input Voltage High	T _A = +25°C	3.6	3.7		V	А
	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	3.5	3.6		V	В
Common-Mode Rejection Ratio (CMRR)		80	102		dB	А
Input Impedance			100 0.7		kΩpF	С
OUTPUT						
Output Voltage Low	T _A = +25°C		0.10	0.15	V	А
	$T_{A} = -40^{\circ}C \text{ to } +85^{\circ}C$		0.115	0.2	V	В
Output Voltage High	T _A = +25°C	4.7	4.75		V	А
	$T_{A} = -40^{\circ}C \text{ to } +85^{\circ}C$	4.65	4.7		V	В
Output Current Drive (for linear operation)	$R_L = 50 \ \Omega$		±55		mA	С
POWER SUPPLY			1	1	1	
Specified Operating Voltage		2.5		5.5	V	В
Quiescent Operating Current, per channel	T _A = +25°C	0.95	1.14	1.25	mA	А
	$T_A = -40^{\circ}C$ to $+85^{\circ}C$	0.9	1.15	1.3	mA	В
Power-Supply Rejection Ratio (±PSRR)		80	100		dB	А
POWER DOWN						
Enable Voltage Threshold	Ensured <i>on</i> above 2.1 V		1.6	2.1	V	А
Disable Voltage Threshold	Ensured off below 0.7 V	0.7	1.6		V	А
Disable Pin Bias Current			1		μA	С
Power Down Quiescent Current			20		μA	С
Turn-On Time Delay	Time to V_{OUT} = 90% of final value, V_IN= 2 V, R_L = 200 Ω		70		ns	В
Turn-Off Time Delay	Time to V_{OUT} = 10% of original value, V_{IN} = 2 V, R_L = 200 Ω		60		ns	В
V _{OCM} VOLTAGE CONTROL						
Small-Signal Bandwidth			23		MHz	С
Slew Rate			55		V/µs	С
Gain		0.98	0.99	1.02	V/V	А
Common-Mode Offset Voltage from V_{OCM} Input	Measured at V_{OUT} with V_{OCM} input driven, V_{OCM} = 2.5V ±1 V		±5	±9	mV	В
Input Bias Current	$V_{OCM} = 2.5V \pm 1 V$		±20	±25	μA	В
V _{OCM} Voltage Range		1	0.8 to 4.2	4	V	А
Input Impedance			46 1.5		kΩ	С
Default Output Common-Mode Voltage Offset from (V_S+- V_S-)/2	Measured at V_{OUT} with V_{OCM} input open		±1	±5	mV	А
THERMAL CHARACTERISTICS						
Specified Operating Range All Packages		-40		+85	°C	С
Thermal Resistance, θ_{JA}	Junction-to-ambient					
THS4521 D SO-8			194		°C/W	С
DGK MSOP-8			269		°C/W	С
THS4522 PW TSSOP-16			116		°C/W	С
THS4524 DBT TSSOP-38			81		°C/W	С

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DEVICE INFORMATION





TERMINAL FUNCTIONS: THS4521

SOIC-8,	SOIC-8, MSOP-8	
PIN NO.	NAME	DESCRIPTION
1	V _{IN-}	Inverting amplifier input
2	V _{OCM}	Common-mode voltage input
3	V _{S+}	Amplifier positive power-supply input
4	V _{OUT+}	Noninverting amplifier output
5	V _{OUT-}	Inverting amplifier output
6	V _{S-}	Amplifier negative power-supply input. Note that V_{S-} is tied together on multi-channel devices.
7	PD	Power down. \overline{PD} = logic low puts device into low-power mode. \overline{PD} = logic high or open for normal operation.
8	V _{IN+}	Noninverting amplifier input

TERMINAL FUNCTIONS: THS4522

TSSC	DP-16	
PIN NO.	NAME	DESCRIPTION
1	PD ₁	Power down 1. \overline{PD} = logic low puts device into low-power mode. \overline{PD} = logic high or open for normal operation.
2	V _{IN1+}	Noninverting amplifier 1 input
3	V _{IN1-}	Inverting amplifier 1 input
4	V _{OCM1}	Common-mode voltage input 1
5	PD ₂	Power down 2. \overline{PD} = logic low puts device into low-power mode. \overline{PD} = logic high or open for normal operation.
6	V _{IN2+}	Noninverting amplifier 2 input
7	V _{IN2-}	Inverting amplifier 2 input
8	V _{OCM2}	Common-mode voltage input 2
9	V _{S+2}	Amplifier 2 positive power-supply input
10	V _{OUT2+}	Noninverting amplifier 2 output
11	V _{OUT2-}	Inverting amplifier 2 output
12	V _{S-}	Negative power-supply input. Note that V_{S-} is tied together on multi-channel devices.
13	V _{S+1}	Amplifier 1 positive power-supply input
14	V _{OUT1+}	Noninverting amplifier 1 output
15	V _{OUT1-}	Inverting amplifier 1 output
16	V _{S-}	Negative power-supply input. Note that V_{S-} is tied together on multi-channel devices.

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THS4524 TSSOP-38 (DBT PACKAGE) (TOP VIEW)





TERMINAL FUNCTIONS: THS4524

TSSOP-38		
PIN NO.	NAME	DESCRIPTION
1	PD ₁	Power down 1. \overline{PD} = logic low puts channel into low-power mode. \overline{PD} = logic high or open for normal operation.
2	V _{IN1+}	Noninverting amplifier 1 input
3	V _{IN1-}	Inverting amplifier 1 input
4	V _{OCM1}	Common-mode voltage input 1
5	V _{S-}	Negative power-supply input. Note that V_{S-} is tied together on multi-channel devices.
6	PD ₂	Power down 2. \overline{PD} = logic low puts channel into low-power mode. \overline{PD} = logic high or open for normal operation.
7	V _{IN2+}	Noninverting amplifier 2 input
8	V _{IN2-}	Inverting amplifier 2 input
9	V _{OCM2}	Common-mode voltage input 2
10	V _{S-}	Negative power-supply input. Note that V_{S-} is tied together on multi-channel devices.
11	PD 3	Power down 3. \overline{PD} = logic low puts channel into low-power mode. \overline{PD} = logic high or open for normal operation.
12	V _{IN3+}	Noninverting amplifier 3 input
13	V _{IN3-}	Inverting amplifier 3 input
14	V _{OCM3}	Common-mode voltage input 3
15	V _{S-}	Negative power-supply input. Note that V_{S-} is tied together on multi-channel devices.
16	PD ₄	Power down 4. \overline{PD} = logic low puts channel into low-power mode. \overline{PD} = logic high or open for normal operation.
17	V _{IN4+}	Noninverting amplifier 4 input
18	V _{IN4-}	Inverting amplifier 4 input
19	V _{OCM4}	Common-mode voltage input 4
20	V _{S4+}	Amplifier 4 positive power-supply input
21	V _{OUT4+}	Noninverting amplifier 4 output
22	V _{OUT4-}	Inverting amplifier 4 output
23	V _{S-}	Negative power-supply input. Note that V_{S-} is tied together on multi-channel devices.
24	V _{S-}	Negative power-supply input. Note that V_{S-} is tied together on multi-channel devices.
25	V _{S3+}	Amplifier 3 positive power-supply input
26	V _{OUT3+}	Noninverting amplifier3 output
27	V _{OUT3-}	Inverting amplifier3 output
28	V _{S-}	Negative power-supply input. Note that V _S is tied together on multi-channel devices.
29	V _{S-}	Negative power-supply input. Note that V _S is tied together on multi-channel devices.
30	V _{S2+}	Amplifier 2 positive power-supply input
31	V _{OUT2+}	Noninverting amplifier 2 output
32	V _{OUT2-}	Inverting amplifier 2 output
33	V _{S-}	Negative power-supply input. Note that V _S is tied together on multi-channel devices.
34	V _{S-}	Negative power-supply input. Note that V _S is tied together on multi-channel devices.
35	V _{S1+}	Amplifier 1 positive power-supply input
36	V _{OUT1+}	Noninverting amplifier 1 output
37	V _{OUT1-}	Inverting amplifier 1 output
38	V _{S-}	Negative power-supply input. Note that V _S is tied together on multi-channel devices.



TYPICAL CHARACTERISTICS

Table of Graphs: $V_{S+} - V_{S-} = 3.3 V$

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Table of Graphs: $V_{S+} - V_{S-} = 5 V$

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TYPICAL CHARACTERISTICS: V_{S+} – V_{S-} = 3.3 V (continued)

At $V_{S+} = +3.3 \text{ V}$, $V_{S-} = 0 \text{ V}$, $V_{OCM} = \text{open}$, $V_{OUT} = 2 \text{ V}_{PP}$ (differential), $R_L = 1 \text{ k}\Omega$ differential, G = 1 V/V, single-ended input, differential output, and input and output referenced to midsupply, unless otherwise noted.



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TYPICAL CHARACTERISTICS: $V_{S+} - V_{S-} = 3.3 V$ (continued)

At $V_{S+} = +3.3 \text{ V}$, $V_{S-} = 0 \text{ V}$, $V_{OCM} = \text{open}$, $V_{OUT} = 2 \text{ V}_{PP}$ (differential), $R_L = 1 \text{ k}\Omega$ differential, G = 1 V/V, single-ended input, differential output, and input and output referenced to midsupply, unless otherwise noted.



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TYPICAL CHARACTERISTICS: $V_{S+} - V_{S-} = 3.3 V$ (continued)



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TYPICAL CHARACTERISTICS: $V_{S+} - V_{S-} = 3.3 V$ (continued)

At $V_{S+} = +3.3 \text{ V}$, $V_{S-} = 0 \text{ V}$, $V_{OCM} = \text{open}$, $V_{OUT} = 2 \text{ V}_{PP}$ (differential), $R_L = 1 \text{ k}\Omega$ differential, G = 1 V/V, single-ended input, differential output, and input and output referenced to midsupply, unless otherwise noted.



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TYPICAL CHARACTERISTICS: 5 V





TYPICAL CHARACTERISTICS: 5 V (continued)





TYPICAL CHARACTERISTICS: 5 V (continued)





TYPICAL CHARACTERISTICS: 5 V (continued)

At $V_{S+} = +5 \text{ V}$, $V_{S-} = 0 \text{ V}$, $V_{OCM} = \text{open}$, $V_{OUT} = 2 \text{ V}_{PP}$ (differential), $R_F = 1 \text{ k}\Omega$, $R_L = 1 \text{ k}\Omega$ differential, G = 1 V/V, single-ended input, differential output, and input and output referenced to midsupply, unless otherwise noted.



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TYPICAL CHARACTERISTICS: 5 V (continued)



TEST CIRCUITS

Overview

The THS4521, THS4522, and THS4524 family is tested with the test circuits shown in this section; all circuits are built using the available THS4521 evaluation module (EVM). For simplicity, power-supply decoupling is not shown; see the layout in the Applications section for recommendations. Depending on the test conditions, component values change in accordance with Table 1 and Table 2, or as otherwise noted. In some cases the signal generators used are ac-coupled and in others they dc-coupled 50- Ω sources. To balance the amplifier when ac-coupled, a $0.22 - \mu F$ capacitor and $49.9 - \Omega$ resistor to ground are inserted across R_{IT} on the alternate input; when dc-coupled, only the $49.9-\Omega$ resistor to ground is added across RIT. A split power supply is used to ease the interface to common test equipment, but the amplifier can be operated in a single-supply configuration as described in the Applications section with no impact on performance. Also, for most of the tests, except as noted, the devices are tested with single-ended inputs and a transformer on the output to convert the differential output to single-ended because common lab test equipment has single-ended inputs and outputs. Similar or better performance can be expected with differential inputs and outputs.

As a result of the voltage divider on the output formed by the load component values, the amplifier output is attenuated. The **Atten** column in Table 2 shows the attenuation expected from the resistor divider. When using a transformer at the output (as shown in Figure 54), the signal sees slightly more loss because of transformer and line loss; these numbers are approximate.

Table 1. Gain Component Values for Single-Ended Input⁽¹⁾

Gain	R _F	R _G	R _{IT}
1 V/V	1 kΩ	1 kΩ	52.3 Ω
2 V/V	1 kΩ	487 Ω	53.6 Ω
5 V/V	1 kΩ	187 Ω	59.0 Ω
10 V/V	1 kΩ	86.6 Ω	69.8 Ω

1. Gain setting includes $50-\Omega$ source impedance. Components are chosen to achieve gain and $50-\Omega$ input termination.

Table 2. Load Component Values For 1:1
Differential to Single-Ended Output Transformer ⁽¹⁾

RL	Ro	R _{ot}	Atten
100 Ω	24.9 Ω	Open	6 dB
200 Ω	86.6 Ω	69.8 Ω	16.8 dB
499 Ω	237 Ω	56.2 Ω	25.5 dB
1 kΩ	487 Ω	52.3 Ω	31.8 dB

1. Total load includes $50-\Omega$ termination by the test equipment. Components are chosen to achieve load and $50-\Omega$ line termination through a 1:1 transformer.

Frequency Response

The circuit shown in Figure 53 is used to measure the frequency response of the circuit.

An HP network analyzer is used as the signal source and the measurement device. The output impedance of the HP network analyzer is is dc-coupled and is 50 Ω . R_{IT} and R_G are chosen to impedance-match to 50 Ω and maintain the proper gain. To balance the amplifier, a 49.9- Ω resistor to ground is inserted across R_{IT} on the alternate input.

The output is probed using a Tektronix high-impedance differential probe across the $953-\Omega$ resistor and referred to the amplifier output by adding back the 0.42-dB because of the voltage divider on the output.



Figure 53. Frequency Response Test Circuit



Distortion

The circuit shown in Figure 54 is used to measure harmonic and intermodulation distortion of the amplifier.

An HP signal generator is used as the signal source and the output is measured with a Rhode and Schwarz spectrum analyzer. The output impedance of the HP signal generator is ac-coupled and is 50 Ω . R_{IT} and R_G are chosen to impedance match to 50 Ω and maintain the proper gain. To balance the amplifier, a 0.22-µF capacitor and 49.9- Ω resistor to ground are inserted across R_{IT} on the alternate input.

A low-pass filter is inserted in series with the input to reduce harmonics generated at the signal source. The level of the fundamental is measured and then a high-pass filter is inserted at the output to reduce the fundamental so it does not generate distortion in the input of the spectrum analyzer.

The transformer used in the output to convert the signal from differential to single-ended is an ADT1–1WT. It limits the frequency response of the circuit so that measurements cannot be made below approximately 1 MHz.



Figure 54. Distortion Test Circuit

Slew Rate, Transient Response, Settling Time, Output Impedance, Overdrive, Output Voltage, and Turn-On/Turn-Off Time

The circuit shown in Figure 55 is used to measure slew rate, transient response, settling time, output impedance, overdrive recovery, output voltage swing, and ampliifer turn-on/turn-off time. Turn-on and turn-off time are measured with the same circuit modified for $50-\Omega$ input impedance on the PD input by replacing the $0.22-\mu$ F capacitor with a $49.9-\Omega$ resistor. For output impedance, the signal is injected at V_{OUT} with V_{IN} open; the drop across the 2x 49.9- Ω resistors is then used to calculate the impedance seen looking into the amplifier output.



Figure 55. Slew Rate, Transient Response, Settling Time, Output Impedance, Overdrive Recovery, V_{OUT} Swing, and Turn-On/Turn-Off Test Circuit

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Common-Mode and Power-Supply Rejection

The circuit shown in Figure 56 is used to measure the CMRR. The signal from the network analyzer is applied common-mode to the input. Figure 57 is used to measure the PSRR of V_{S+} and V_{S-}. The power supply under test is applied to the network analyzer dc offset input. For both CMRR and PSRR, the output is probed using a Tektronix high-impedance differential probe across the 953- Ω resistor and referred to the amplifier output by adding back the 0.42-dB as a result of the voltage divider on the output. For these tests, the resistors are matched for best results.



Figure 56. CMRR Test Circuit



Figure 57. PSRR Test Circuit

V_{OCM} Input

The circuit illustrated in Figure 58 is used to measure the frequency response and input impedance of the V_{OCM} input. Frequency response is measured using a Tektronix high-impedance differential probe, with $R_{CM} = 0 \ \Omega$ at the common point of V_{OUT+} and V_{OUT+} , formed at the summing junction of the two matched 499- Ω resistors, with respect to ground. The input а impedance is measured using Tektronix high-impedance differential probe at the V_{OCM} input with $R_{CM} = 10 \ k\Omega$ and the drop across the 10-k Ω resistor is used to calculate the impedance seen looking into the amplifier V_{OCM} input.

The circuit shown in Figure 59 measures the transient response and slew rate of the V_{OCM} input. A 1-V step input is applied to the V_{OCM} input and the output is measured using a 50- Ω oscilloscope input referenced back to the amplifier output.



Figure 58. V_{OCM} Input Test Circuit



Figure 59. V_{OCM} Transient Response and Slew Rate Test Circuit



APPLICATION INFORMATION

The following circuits show application information for the THS4521, THS4522, and THS4524 family. For simplicity, power-supply decoupling capacitors are not shown in these diagrams; see the *EVM* and *Layout Recommendations* section for suggested guidelines. For more details on the use and operation of fully differential op amps, refer to the Application Report Fully-Differential Amplifiers (SLOA054), available for download from the TI web site at www.ti.com.

Differential Input to Differential Output Amplifier

The THS4521, THS4522, and THS4524 family are fully-differential operational amplifiers that can be used to amplify differential input signals to differential output signals. Figure 60 shows a basic block diagram of the circuit (V_{OCM} and \overline{PD} inputs not shown). The gain of the circuit is set by R_F divided by R_G .



Figure 60. Differential Input to Differential Output Amplifier

Single-Ended Input to Differential Output Amplifier

The THS4521, THS4522, and THS4524 family can also amplify and convert single-ended input signals to differential output signals. Figure 61 illustrates a basic block diagram of the circuit (V_{OCM} and \overline{PD} inputs not shown). The gain of the circuit is again set by R_F divided by R_G .



Figure 61. Single-Ended Input to Differential Output Amplifier

Input Common-Mode Voltage Range

The input common-mode voltage of a fully-differential op amp is the voltage at the + and - input pins of the device.

It is important to not violate the input common-mode voltage range (V_{ICR}) of the op amp. Assuming the op amp is in linear operation, the voltage across the input pins is only a few millivolts at most. Therefore, finding the voltage at one input pin determines the input common-mode voltage of the op amp.

Treating the negative input as a summing node, the voltage is given by Equation 1:

$$V_{OUT+} \times \left(\frac{R_{G}}{R_{G} + R_{F}} \right) + \left(V_{IN-} \times \frac{R_{F}}{R_{G} + R_{F}} \right)$$
(1)

To determine the V_{ICR} of the op amp, the voltage at the negative input is evaluated at the extremes of V_{OUT+} . As the gain of the op amp increases, the input common-mode voltage becomes closer and closer to the input common-mode voltage of the source.

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Setting the Output Common-Mode Voltage

The output common-model voltage is set by the voltage at the V_{OCM} pin. The internal common-mode control circuit maintains the output common-mode voltage within 5-mV offset (typ) from the set voltage. If left unconnected, the common-mode set point is set to midsupply by internal circuitry, which may be overdriven from an external source. Figure 62 represents the V_{OCM} input. The internal V_{OCM} circuit has typically 23 MHz of -3 dB bandwidth, which is required for best performance, but it is intended to be a dc bias input pin. A 0.22- μ F bypass capacitor is recommended on this pin to reduce noise. The external current required to overdrive the internal resistor divider is given approximately by the formula in Equation 2:

$$I_{EXT} = \frac{2V_{OCM} - (V_{S+} - V_{S-})}{50 \text{ k}\Omega}$$
(2)

where:

• V_{OCM} is the voltage applied to the V_{OCM} pin



Figure 62. V_{OCM} Input Circuit

Typical Performance Variation with Supply Voltage

The THS4521, THS4522, and THS4524 family of devices provide excellent performance across the specified power-supply range of 2.5 V to 5.5 V with only minor variations. The input and output voltage compliance ranges track with the power supply in nearly a 1:1 correlation. Other changes can be observed in slew rate, output current drive, open-loop gain, bandwidth, and distortion. Table 3 shows the typical variation to be expected in these key performance parameters.

Single-Supply Operation

To facilitate testing with common lab equipment, the THS4521EVM allows for split-supply operation; most of the characterization data presented in this data sheet is measured using split-supply power inputs. The device can easily be used with a single-supply power input without degrading performance.

Figure 63 shows a dc-coupled single-supply circuit with single-ended inputs. This circuit can also be applied to differential input sources.



Figure 63. THS4521 DC-Coupled Single-Supply with Single-Ended Inputs

The input common-mode voltage range of the THS4521, THS4522, and THS4524 family is designed to include the negative supply voltage. in the circuit shown in Figure 63, the signal source is referenced to ground. V_{OCM} is set by an external control source or, if left unconnected, the internal circuit defaults to midsupply. Together with the input impedance of the amplifier circuit, R_{IT} provides input termination, which is also referenced to ground.

Note that R_{IT} and optional matching components are added to the alternate input to balance the impedance at signal input.

PARAMETER	V _S = 5 V	V _S = 3.3 V	V _S = 2.5 V			
-3-dB Small-signal bandwidth	145 MHz	135 MHz	125 MHz			
Slew rate (2-V step)	490 V/μs	420 V/µs	210 V/µs			
Harmonic distortion at 1 MHz, 2 V_{PP} , R_L = 1 k Ω						
Second harmonic	-85 dBc	-85 dBc	-84 dBc			
Third harmonic	–91 dBc	–90 dBc	-88 dBc			
Open-loop gain	119 dB	116 dB	115 dB			
Linear output current drive	55 mA	35 mA	24 mA			

Table 3. Typical Per	formance Variation	versus Power-S	Supply Voltage
----------------------	--------------------	----------------	----------------



Low-Power Applications and the Effects of Resistor Values on Bandwidth

For low-power operation, it may be necessary to increase the gain setting resistors values to limit current consumption and not load the source. Using larger value resistors lowers the bandwidth of the THS4521, THS4522, and THS4524 family as a result of the interactions between the resistors, the device parasitic capacitance, and printed circuit board (PCB) parasitic capacitance. Figure 64 shows the small-signal frequency response with 1-k Ω , 10-k Ω , and 100-k Ω resistors for R_F, R_G, and R_L (impedance is assumed to typically increase for all three resistors in low-power applications).





Frequency Response Variation due to Package Options

Users can see variations in the small-signal (V_{OUT} = 100 mV_{PP}) frequency response between the available package options for the THS4521, THS4522, and THS4524 family as a result of parasitic elements associated with each package and board layout changes. Figure 65 shows the variance measured in the lab; this variance is to be expected even when using a good layout.



Figure 65. Small-Signal Frequency Response: Package Variations

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Driving Capacitive Loads

The THS4521, THS4522, and THS4524 family is designed for a nominal capacitive load of 1 pF on each output to ground. When driving capacitive loads greater than 1 pF, it is recommended to use small resistors (R_0) in series with the output, placed as close to the device as possible. Without R_0 , capacitance on the output interacts with the output impedance of the amplifier and causes phase shift in the loop gain of the amplifier that reduces the phase margin.

This reduction in phase margin results in frequency response peaking; overshoot, undershoot, and/or ringing when a step or square-wave signal is applied; and may lead to instability or oscillation. Inserting R_O isolates the phase shift from the loop gain path and restores the phase margin, but it also limits bandwidth. Figure 66 shows the recommended values of R_O versus capacitive loads (C_L). Figure 67 shows the frequency response with various values.



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Figure 67. Frequency Response for Various R_0 and C_L Values, with R_{LOAD} = 1 k Ω

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Audio Performance

The THS4521, THS4522, and THS4524 family provide excellent audio performance with very low quiescent power. To show performance in the audio band, the device was tested with a SYS-2722 audio analyzer from Audio Precision. THD+N and FFT tests were performed at 1-V_{RMS} output voltage. Performance is the same on both 3.3-V and 5-V supplies. Figure 68 shows the test circuit used; Figure 69 and Figure 70 show the performance of the analyzer using internal loopback mode (generator) together with the THS4521. Note that the harmonic distortion performance is very close to the same with and without the device meaning the THS4521 performance is actually much better than can be directly measured by this meathod. Using these measurements and simuation, we estimate the second-order harmonic distortion to be -133 dBc and the third-order harmonic distortion to be -140 dBc at 10 kHz. Note that the circuit of Figure 68 is also used to measure crosstalk between channels on the THS4522 and THS4524 using the crosstalk meter function of the AP audio analyzer.



Figure 68. THS4521 AP Analyzer Test Circuit

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Figure 69. THS4521 1-V_{RMS} 20-Hz to 20-kHz THD+N



Figure 70. THS4521 1-V_{RMS} 10-kHz FFT Plot

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ADC Driver Performance: THS4521 and ADS1278 Combined Performance

The THS4521 provides excellent performance when driving high-performance delta-sigma ($\Delta\Sigma$) and successive approximation register (SAR) ADCs in audio and industrial applications using a single 3-V to 5-V power supply. To show achievable performance, the THS4521 is tested as the drive amplifier for the ADS1278 24-bit ADC. The ADS1278 offers excellent ac and dc performance, with four selectable operating modes from 10 kSPS to 128 kSPS to enable the user to fine-tune performance and power for specific application needs. The circuit shown in Figure 71 was used to test the performance. Data were taken using the High-Resolution mode (52 kSPS) of the ADS1278 with input frequencies at 1 kHz and 10 kHz and signal levels 1/2 dB below full-scale (-0.5 dBFS). FFT plots showing the spectral performance are given in Figure 72 and Figure 73; tabulated ac analysis results are shown in Table 4.



Figure 71. THS4521 and ADS1278 (Ch 1) Test Circuit



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Figure 72. 1-kHz FFT



Figure 73. 10-kHz FFT

Tone (Hz)	Signal (dBFS)	SNR (dBc)	THD (dBc)	SINAD (dBc)	SFDR (dBc)
1 k	-0.50	109.1	-107.9	105.5	113.7
10 k	-0.50	101.8	-109.8	101.1	109.8



ADC Driver Performance: THS4521 and ADS8321 Combined Performance

To demonstrate achievable performance, the THS4521 is tested as the drive amplifier for the ADS8321 16-bit SAR ADC. The ADS8321 offers excellent ac and dc performance, with ultra-low power and small size. The circuit shown in Figure 74 was used to test the performance. Data were taken using the ADS8321 at 100 kSPS with input frequencies of 2 kHz and 10 kHz and signal levels that were -0.5 dBFS. FFT plots that illustrate the spectral performance are given in Figure 75 and Figure 76. Tabulated ac analysis results are listed in Table 5.



Figure 74. THS4521 and ADS8321 Test Circuit



Figure 75. 2-kHZ FFT

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Figure 76. 10-kHz FFT

Table 5. AC Analysis

Tone (Hz)	Signal (dBFS)	SNR (dBc)	THD (dBc)	SINAD (dBc)	SFDR (dBc)
2 k	-0.5	86.7	-97.8	86.4	100.7
10 k	-0.6	85.2	-98.1	85.2	102.2



EVM AND LAYOUT RECOMMENDATIONS

Figure 77 shows the THS4521EVM schematic. PCB layers 1 through 4 are shown in Figure 78; Table 6 lists the bill of materials for the THS4521EVM as supplied from TI. It is recommended to follow the layout of the external components near to the amplifier, ground plane construction, and power routing as closely as possible. Follow these general guidelines:

- 1. Signal routing should be direct and as short as possible into and out of the op amp circuit.
- 2. The feedback path should be short and direct.
- 3. Ground or power planes should be removed from directly under the amplifier input and output pins.
- 4. An output resistor is recommended in each output lead, placed as near to the output pins as possible.
- 5. Two $0.1-\mu F$ power-supply decoupling capacitors should be placed as near to the power-supply pins as possible.
- 6. Two 10-μF power-supply decoupling capacitors should be placed within 1 inch of the device and can be shared among multple analog devices.
- A 0.22-μF capacitor should be placed between the V_{OCM} input pin and ground near to the pin. This capacitor limits noise coupled into the pin.
- 8. The PD pin uses TTL logic levels; a bypass capacitor is not necessary if actively driven, but can be used for robustness in noisy environments whether driven or not.
- 9. If input termination resistors R_{10} and R_{11} are used, a single point connection to ground on L2 is recommended.



Figure 77. THS4521EVM: Schematic



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THS4521

THS4522



Figure 78. THS4521EVM: Layer 1 to Layer 4 Images



Table 6. THS4521EVM Parts List

ITEM	DESCRIPTION	SMD SIZE	REFERENCE DESIGNATOR	QTY	MANUFACTURER PART NUMBER
1	Capacitor, 10.0 µF, ceramic, X5R, 6.3 V	0805	C7, C8, C9, C10	4	(AVX) 08056D106KAT2A
2	Capacitor, 0.1 µF, ceramic, X7R, 16 V	0603	C3, C5, C11, C12	4	(AVX) 0603YC104KAT2A
3	Capacitor, 0.22 µF, ceramic, X7R, 10 V	0603	C1, C4, C6	3	(AVX) 0603ZC224KAT2A
4	Open	0603	C2, C13, C14, C15, C16	5	
5	Open	0603	R1, R2, R3, R7, R8, R9, R18, R19, R21, R22, R23, R26	12	
6	Resistor, 0 Ω	0603	R24, R25	2	(ROHM) MCR03EZPJ000
7	Resistor, 49.9 Ω, 1/10W, 1%	0603	R6	1	(ROHM) MCR03EZPFX49R9
8	Resistor, 52.3 Ω, 1/10W, 1%	0603	R10, R11, R20	3	(ROHM) MCR03EZPFX52R3
9	Resistor, 487 Ω, 1/10W, 1%	0603	R16, R17	2	(ROHM) MCR03EZPFX4870
10	Resistor, 1k Ω, 1/10W, 1%	0603	R12, R13, R14, R15	4	(ROHM) MCR03EZPFX1001
11	Resistor, 0 Ω	0805	R4, R5	2	(ROHM) MCR10EZPJ000
12	Open		T1	1	
13	Transformer, RF		T2	1	(MINI-CIRCUITS) ADT1-1WT
14	Jack, Banana receptance, 0.25-in dia. hole		J4, J5, J8	3	(SPC) 813
15	Open		J1, J3, J6, J7, J10, J11	6	
16	Connector, edge, SMA PCB jack		J2, J9	2	(JOHNSON) 142-0701-801
17	Header, 0.1 in CTRS, 0.025-in sq. pins	2 POS.	JP1	1	(SULLINS) PBC36SAAN
18	Shunts		JP1	1	(SULLINS) SSC02SYAN
19	Test point, Red		TP1	1	(KEYSTONE) 5000
20	Test point, Black		TP2, TP3	2	(KEYSTONE) 5001
21	IC, THS4521		U1	1	(TI) THS4521D
22	Standoff, 4-40 hex, 0.625 in length			4	(KEYSTONE) 1808
23	Screw, Phillips, 4-40, .250 in			4	SHR-0440-016-SN
24	Board, printed circuit			1	(TI) EDGE# 6494532



THS4521 THS4522 THS4524 SBOS458B-DECEMBER 2008-REVISED MAY 2009

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EVM WARNINGS AND RESTRICTIONS

It is important to operate this EVM within the input voltage range of 3 V to 5.5 V and the output voltage range of 3 V to 5.5 V.

Exceeding the specified input range may cause unexpected operation and/or irreversible damage to the EVM. If there are questions concerning the input range, please contact a TI field representative prior to connecting the input power.

Applying loads outside of the specified output range may result in unintended operation and/or possible permanent damage to the EVM. Please consult the EVM User's Guide prior to connecting any load to the EVM output. If there is uncertainty as to the load specification, please contact a TI field representative.

During normal operation, some circuit components may have case temperatures greater than +85°C. The EVM is designed to operate properly with certain components above +85°C as long as the input and output ranges are maintained. These components include but are not limited to linear regulators, switching transistors, pass transistors, and current sense resistors. These types of devices can be identified using the EVM schematic located in the EVM User's Guide. When placing measurement probes near these devices during operation, please be aware that these devices may be very warm to the touch.

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Page

Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Cł	hanges from Revision A (March, 2009) to Revision B	Page
•	Corrected ordering number for THS4522 large tape and reel	2

Changes from Original (December, 2008) to Revision A

٠	Changed device status of THS4524 from product preview to production data	1
•	Changed power-supply voltage range from +3 V (1.5 V) to +2.5 V (1.25 V)	1
٠	Revised channel-to-channel crosstalk specifications (3.3 V)	3
•	Changed specified operating voltage (3.3 V) from 3 V (minimum) to 2.5 V (minimum)	4
٠	Revised channel-to-channel crosstalk specifications (5 V)	5
•	Changed specified operating voltage (5 V) from 3 V (minimum) to 2.5 V (minimum)	6
٠	Updated Figure 18 (THS4522, THS4524 Crosstalk)	. 14
•	Updated Figure 44 (THS4522, THS4524 Crosstalk)	. 19
•	Added Typical Performance Variation with Supply Voltage section	. 26
•	Changed title of Single-Supply Operation section	. 26
•	Added sentence regarding use of Figure 68 to measure crosstalk between channels of THS4522 and THS4524 to Audio Performance section	. 29
•	Corrected device name error in EVM schematic	. 32

PACKAGING INFORMATION

RUMENTS

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
THS4521ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
THS4521IDGKR	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
THS4521IDGKT	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
THS4521IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
THS4522IPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
THS4522IPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
THS4524IDBT	ACTIVE	TSSOP	DBT	38	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
THS4524IDBTR	ACTIVE	TSSOP	DBT	38	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

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⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nomina	I											
Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
THS4521IDGKR	MSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
THS4521IDGKT	MSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
THS4521IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
THS4522IPWR	TSSOP	PW	16	2000	330.0	12.4	7.0	5.6	1.6	8.0	12.0	Q1
THS4524IDBTR	TSSOP	DBT	38	2000	330.0	16.4	6.9	10.2	1.8	12.0	16.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

27-May-2009



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
THS4521IDGKR	MSOP	DGK	8	2500	346.0	346.0	29.0
THS4521IDGKT	MSOP	DGK	8	250	190.5	212.7	31.8
THS4521IDR	SOIC	D	8	2500	346.0	346.0	29.0
THS4522IPWR	TSSOP	PW	16	2000	346.0	346.0	29.0
THS4524IDBTR	TSSOP	DBT	38	2000	346.0	346.0	33.0

MECHANICAL DATA

MTSS001C - JANUARY 1995 - REVISED FEBRUARY 1999

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.

Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.

E. Reference JEDEC MS-012 variation AA.



DGK (S-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 per end.

- D Body width does not include interlead flash. Interlead flash shall not exceed 0.50 per side.
- E. Falls within JEDEC MO-187 variation AA, except interlead flash.



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